2309412-1 ACTIVE

DDR4 DIMM

TE Internal #: 2309412-1

Small Outline (SO), Stack Height 8 mm [.315 in], Right Angle Module Orientation, 260 Position, DDR4 DIMM, SO DIMM Sockets

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR4 SO DIMM Sockets



DRAM Type: Small Outline (SO) Stack Height: 8 mm [.315 in] Module Orientation: Right Angle

Number of Positions: 260

Centerline (Pitch): 6.1 mm, .5 mm, 5.4 mm [.02 in]

All DDR4 SO DIMM Sockets (39)

Features

| Electrical Characteristics | |
|----------------------------|----------------|
| DRAM Voltage | 1.2 V |
| Industry Standards | |
| UL Flammability Rating | UL 94V-0 |
| Termination Features | |
| Insertion Style | Cam-In |
| Termination Method to PCB | Surface Mount |
| Mechanical Attachment | |
| Connector Mounting Type | Board Mount |
| PCB Mount Retention Type | Solder Peg |
| Mating Alignment Type | Reverse Keying |
| PCB Mount Retention | With |
| Signal Characteristics | |
| SGRAM Voltage | 1.2 V |
| Packaging Features | |
| Packaging Quantity | 500 |

Tape & Reel

Packaging Method



Contact Features

| Contact Current Rating (Max) | .5 A |
|---|--------------|
| Contact Underplating Material | Nickel |
| Memory Socket Type | Memory Card |
| Contact Base Material | Copper Alloy |
| PCB Contact Termination Area Plating Material | Gold Flash |
| Contact Mating Area Plating Material | Gold Flash |

Body Features

| Retention Post Location | Both Ends |
|-------------------------|--------------------------------|
| Retention Post Material | Stainless Steel |
| Latch Material | High Temperature Thermoplastic |
| Module Key Type | Offset Right |
| Ejector Type | Locking |
| Ejector Location | Both Ends |
| Connector Profile | High |

Housing Features

| Housing Material | High Temperature Thermoplastic |
|--------------------|--------------------------------|
| Housing Color | Black |
| Centerline (Pitch) | 6.1 mm, .5 mm, 5.4 mm[.02 in] |

Configuration Features

| Number of Keys | 1 |
|---------------------|-------------|
| Number of Rows | 2 |
| Module Orientation | Right Angle |
| Number of Positions | 260 |

Product Type Features

| Connector & Contact Terminates To | Printed Circuit Board |
|-----------------------------------|-----------------------|
| Connector System | Cable-to-Board |
| DRAM Type | Small Outline (SO) |

Dimensions

| Stack Height | 8 mm[.315 in] |
|--------------------|-----------------|
| Row-to-Row Spacing | 8.2 mm[.322 in] |

Usage Conditions



| Operating Temperature Range | -55 – 85 °C[-67 – 185 °F] |
|-----------------------------|---------------------------|
| Operation/Application | |
| Circuit Application | Power |
| Other | |
| EU RoHS Compliance | Compliant |
| EU ELV Compliance | Compliant |

Product Compliance

For compliance documentation, visit the product page on TE.com>

| EU RoHS Directive 2011/65/EU | Compliant |
|---|---|
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Reflow solder capable to 260°C |

Product Compliance Disclaimer

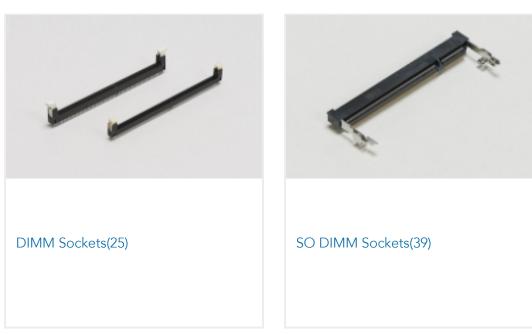
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

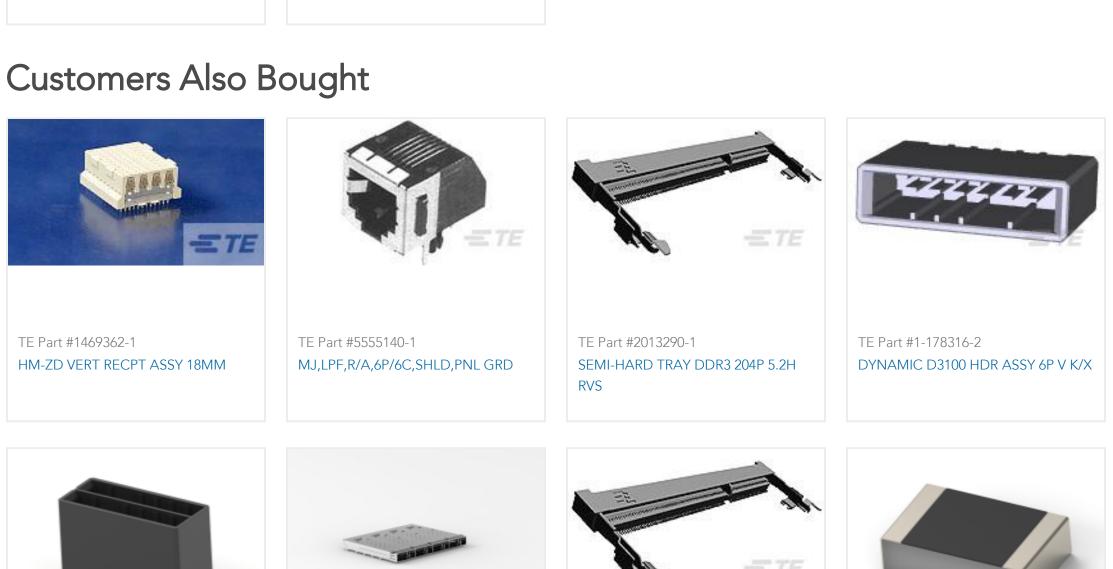
Compatible Parts





Also in the Series DDR4 DIMM

















Documents

Product Drawings

DDR4 SODIMM 260P 8.0H RVS

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2309412-1_1.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2309412-1_1.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2309412-1_1.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Application Specification

English